Meeting Summary and Minutes

Japan Standards Winter 2016 Meetings in conjunction with SEMICON Japan 2016
Friday, December 16, 2016, 13:00 - 16:30
Tokyo Big Sight Conference Tower, Tokyo, Japan

TC Chapter Announcements

Next TC Chapter Meeting
Friday, April 21, 2017, 13:30-17:00
SEMI Japan office, Tokyo, Japan

Table 1 Meeting Attendees

*Italicics* indicate virtual participants

**Co-Chairs:** Takayuki Nishimura (SCREEN Semiconductor Solutions), Mitsuhiro Matsuda (Hitachi Kokusai Electric)

**SEMI Staff:** Chie Yanagisawa

<table>
<thead>
<tr>
<th>Company</th>
<th>Last</th>
<th>First</th>
<th>Company</th>
<th>Last</th>
<th>First</th>
</tr>
</thead>
<tbody>
<tr>
<td>Hitachi High-Technologies</td>
<td>Toyoshima</td>
<td>Yuko</td>
<td>Tokyo Electron</td>
<td>Asakawa</td>
<td>Terry</td>
</tr>
<tr>
<td>Hitachi Kokusai Electric</td>
<td>Matsuda</td>
<td>Mitsuhiro</td>
<td>Tokyo Electron</td>
<td>Mochizuki</td>
<td>Tadashi</td>
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<tr>
<td>Lasertec</td>
<td>Yano</td>
<td>Shingo</td>
<td>Tokyo Electron</td>
<td>Murata</td>
<td>Naoko</td>
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<tr>
<td>Murata Machinery</td>
<td>Imoto</td>
<td>Shinichiro</td>
<td>SEMI Headquarters</td>
<td>Amano</td>
<td>James</td>
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<tr>
<td>Nippon Pulse Motor</td>
<td>Terasaki</td>
<td>Takashi</td>
<td>SEMI Korea</td>
<td>Shim</td>
<td>Natalie</td>
</tr>
<tr>
<td>SCREEN Semiconductor Solutions</td>
<td>Nishimura</td>
<td>Takayuki</td>
<td>SEMI Taiwan</td>
<td>Chang</td>
<td>Dean</td>
</tr>
<tr>
<td>SCREEN Semiconductor Solutions</td>
<td>Takasaki</td>
<td>Yoshihisa</td>
<td>SEMI Japan</td>
<td>Yanagisawa</td>
<td>Chie</td>
</tr>
</tbody>
</table>

Table 2 Leadership Changes

<table>
<thead>
<tr>
<th>WG/TF/SC/TC Name</th>
<th>Previous Leader</th>
<th>New Leader</th>
</tr>
</thead>
<tbody>
<tr>
<td>Equipment Information System Security (EISS) TF</td>
<td>Mitsune Sakamoto (Consultant)</td>
<td>No leader due to the TF’s discharge</td>
</tr>
</tbody>
</table>

Table 3 Committee Structure Changes

<table>
<thead>
<tr>
<th>Previous WG/TF/SC Name</th>
<th>New WG/TF/SC Name or Status Change</th>
</tr>
</thead>
<tbody>
<tr>
<td>Equipment Information System Security (EISS) TF</td>
<td>Discharged</td>
</tr>
</tbody>
</table>
Table 4 Ballot Results

<table>
<thead>
<tr>
<th>Document #</th>
<th>Document Title</th>
<th>Committee Action</th>
</tr>
</thead>
<tbody>
<tr>
<td>#5973</td>
<td>Line Item Revisions to SEMI E170-0416: Specification for Secured Foundation of</td>
<td>--</td>
</tr>
<tr>
<td></td>
<td>Recipe Management System (SFORMS)</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Line Item 1 Revise the format of ‘Service Message Description Table’.</td>
<td>Passed as balloted</td>
</tr>
<tr>
<td></td>
<td>Line Item 2 Correct editorial errors in ‘Table 46 Compliance Statement’.</td>
<td>Passed as balloted</td>
</tr>
<tr>
<td></td>
<td>Line Item 3 Add a section ‘Required Items for Each Implementation Step’ which</td>
<td>Failed and work will be discontinued.</td>
</tr>
<tr>
<td></td>
<td>provides a checklist of required items for each implementation step in Related Information.</td>
<td></td>
</tr>
</tbody>
</table>

Note 1: Passed ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.
Note 2: Failed ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Activities Approved by the GCS prior to the Originating TC Chapter meeting

<table>
<thead>
<tr>
<th>#</th>
<th>Type</th>
<th>SC/TF/WG</th>
<th>Details</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
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</tbody>
</table>

Table 6 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

<table>
<thead>
<tr>
<th>#</th>
<th>SC/TF/WG</th>
<th>Details</th>
<th></th>
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</thead>
<tbody>
<tr>
<td>#6089</td>
<td>GEM300 TF</td>
<td>Revision to the SNARF: Line Item Revision to SEMI E170.1-0416 and SEMI E5-0813</td>
<td></td>
</tr>
<tr>
<td>#6091</td>
<td>GEM300 TF</td>
<td>Revision to the SNARF: Line Item Revision to SEMI E174-1116: Specification for Wafer Job Management (WJM)</td>
<td></td>
</tr>
</tbody>
</table>

Note 1: SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 7 Authorized Ballots

<table>
<thead>
<tr>
<th>#</th>
<th>When</th>
<th>TF</th>
<th>Details</th>
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<tbody>
<tr>
<td>#6090</td>
<td>Cycle 2-2017</td>
<td>Japan I&amp;C Maintenance TF</td>
<td>Line Item Revision to SEMI E91-0600 (Reapproved 1109) “SPECIFICATION FOR PROBER SPECIFIC EQUIPMENT MODEL (PSEM)”</td>
<td></td>
</tr>
<tr>
<td>#6089</td>
<td>Cycle 2-2017</td>
<td>GEM300 TF</td>
<td>Line Item Revision to “SEMI E170.1-0416 SPECIFICATION FOR SECS-II PROTOCOL FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM”, “SEMI E170-0416, SPECIFICATION FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM (SFORMS)” and “SEMI E5-0813 SEMI EQUIPMENT COMMUNICATIONS STANDARD 2 MESSAGE CONTENT (SECS-II)” with title change.</td>
<td></td>
</tr>
<tr>
<td>#6091</td>
<td>Cycle 2-2017</td>
<td>GEM300 TF</td>
<td>Line Item Revision to SEMI E174-1116: Specification for Wafer Job Management (WJM)</td>
<td></td>
</tr>
</tbody>
</table>
### Table 8 SNARF(s) Granted a One-Year Extension

<table>
<thead>
<tr>
<th>#</th>
<th>TF</th>
<th>Title</th>
<th>Expiration Date</th>
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<tbody>
<tr>
<td>None</td>
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### Table 9 SNARF(s) Abolished

<table>
<thead>
<tr>
<th>#</th>
<th>TF</th>
<th>Title</th>
</tr>
</thead>
<tbody>
<tr>
<td>None</td>
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### Table 10 Standard(s) to receive Inactive Status

<table>
<thead>
<tr>
<th>Standard Designation</th>
<th>Title</th>
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<tbody>
<tr>
<td>None</td>
<td></td>
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</table>

### Table 11 New Action Items

<table>
<thead>
<tr>
<th>Item #</th>
<th>Assigned to</th>
<th>Details</th>
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</thead>
<tbody>
<tr>
<td>20161216-01</td>
<td>SEMI Korea staff and SEMI Taiwan staff</td>
<td>To send the materials for concept of CUARAM (Centralized User Authentication &amp; Role Authorization Management) that Terry Asakawa (Tokyo Electron) explained at this meeting to the TC members in each region before the upcoming TC Chapter meeting and then to receive feedback from them at the TC Chapter meeting.</td>
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### Table 12 Previous Meeting Action Items

<table>
<thead>
<tr>
<th>Item #</th>
<th>Assigned to</th>
<th>Details</th>
</tr>
</thead>
<tbody>
<tr>
<td>20161021-01</td>
<td>SEMI staff</td>
<td>To ask SEMI Korea staff about the relationship between the published backend Standards such as SEMI E142 and SEMI G81 and the activity of Advanced Back-end Factory Integration Task Force. -&gt; CLOSE</td>
</tr>
<tr>
<td>20161021-02</td>
<td>Co-chairs</td>
<td>To report the issue, that is no email announcement of the I&amp;C Taiwan TC Chapter meeting held on April 8, 2016, to JRSC and submit a letter to JRSC that it will raise this issue to ISC. -&gt; CLOSE</td>
</tr>
<tr>
<td>20161021-03</td>
<td>SEMI Staff</td>
<td>To ask the voter, Brian Rubow (Cimetrix Incorporated), to clarify the point that he does not satisfy of the technical reasons of his Disapprove vote to R5601A because the I&amp;C Japan TC Chapter did not understand the meaning of his technical reasons of this disapprove vote. -&gt; CLOSE</td>
</tr>
</tbody>
</table>
1 Welcome, Reminders, and Introductions

Takayuki Nishimura (SCREEN Semiconductor Solutions) called the meeting to order at 13:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01_Required_Elements_Reg_20150327_E+J

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion: To approve the minutes of the previous meeting as written.

By / 2nd: Mitsuhiro Matsuda (Hitachi Kokusai Electric) / Yoshihisa Takasaki (SCREEN Semiconductor Solutions)

Discussion: None

Vote: 8 in favor and 0 opposed. Motion Passed.

3 Technical Committee Award

Information & Control Japan TC Chapter gave the Technical Committee Awards to the following two members

• Mr. Koji Kitajima / Toshiba for the dedication to the development of GEM300A (SEMI E170, E171 and E174)
• Mr. Shoji Harakawa / Toshiba for the dedication to the development of GEM300A (SEMI E170, E171 and E174)

4 Liaison Reports

4.1 Information & Control Europe TC Chapter

James Amano (SEMI HQ) reported for the Information & Control Europe TC Chapter as attached. Of note:

• Process Control Systems TF
  o No New Activity.
  o No New Ballots.
  o Potential topic: Predictive Model Markup Language (PMML)
    ▪ currently used by other industries, but not in semiconductor

Attachment: 02_EU I&C November 2016 v1

4.2 Information & Control Korea TC Chapter

Natalie Shim (SEMI Korea) reported for the Information & Control Korea TC Chapter. Of note:

• Advanced Back-end Factory Integration TF newly formed.
  o Charter: To develop the equipment automation standards for Backend tools (Bump, Chip Probing, Assembly, Final Test and Sensor) to enable full automation process, including wafer and dice processing tools.
  o Scope:
    ▪ GEM 300 & HSMS Support
    ▪ Dice operational scenario
    ▪ Dice stacking capability and equipment automation specification
- Traceability of multi-wafers, multi-dice operation and raw packaging materials
- Discovery and management of data acquisition configuration
- Discovery of the structure and organization of the equipment and its subsystems and components
- Marking operation
- Standardization for lot indexing on based continuous processing

Participants
- Miracom Inc (Leader), Lam Research, Hanamicon, AIM, Hanmi semiconductor, Kornic Automation, SK hynix, Disco and Shinkawa

STEP for EDA
- Oct 20 at AICT
- Attendee: 47
- Instructor: Hyungsu Kim (Doople)

Upcoming Ballot
- 5832 (Generic Counter Model) in cycle 9.

Attachment: 03_KR_I&C_liaison_Nov

4.3 Information & Control North America TC Chapter

James Amano (SEMI HQ) reported for the Information & Control NA TC Chapter. Of note:

- Diagnostic Data Acquisition Task Force
  - Ballot Adjudication: 6064 E121 – FAILED
  - New/Updated SNARF: #6064
  - Ballot Plans next cycles: 6064A

- Energy Saving Equipment Communication Task Force
  - No meeting during Standards Fall 2016 Meetings and Activities will resume at Standards Spring 2017 Meetings

- GEM300 Task Force
  - Ballot Adjudication – all failed
    - 5549 E30 Title Change, 5872A E172 SEDD Update, 6026, 6066 and 6068
  - New/Updated SNARF(s): 6026, 6066 and 6068, New Large PP Transfer
  - Ballot Plans next cycles: 5549A, 5872B, 5738 E87.1 Provisional and 6066A

- Process Control Systems - Task Force
  - Discussions on ballot 5716 for updates to E133 and E133.1
  - Motion approved to ballot in Cycle 2 2017
  - Potential to pursue additional standardization in Virtual Metrology once International Roadmap for Devices and Systems (IRDS) comes out with their virtual metrology white paper.

- Sensor Bus - Task Force
  - Ballots adjudicated: Ballot 6067 (reapproval)
New business: Reapprovals per direction from the I&CC

- **Graphical User Interfaces Task Force**
  - Leader: Frank Summers (ISGI)
  - New TFOF approved during SEMICON West 2016
  - First meeting during Fall 2016
    - Reviewed & discussed GUI TFOF activities development plan
    - Defined the scope for major revision to SEMI E95
    - Updated new SNARF for E95 revision
  - New SNARF(s):
    - Revision to SEMI E95-1101-0307R, *Specification for Human Interface for Semiconductor Manufacturing Equipment*
      - SNARF will be resent to global members for 2-week review and GCS for approval
  - Ballot Adjudication: None
  - Ballot Plans Next Cycles: None

**Attachment:** 04_NA I&C Liaison Report Dec 2016

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4.4 *Information & Control Taiwan TC Chapter*

Dean Chang (SEMI Taiwan) reported for the Information & Control Taiwan TC Chapter. Of note:

- Equipment Information Integration TF Task Force
  - The Task Force currently has no activities.
- GEM300 TF
  - The Task Force currently has no activities.
- Backend Factory Integration TF
  - Studied the feedback of New SNARF “Specification of Backend Die Traceability” from the I&C global TC members and will discuss with TF members how to modify this SNARF.

**Attachment:** 05_Taiwan_I&C Standards Committee Liaison Report Nov 2016

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4.5 *SEMI Staff Report*

Chie Yanagisawa (SEMI Japan) gave the SEMI Staff Report. Of note:

- SEMI Global 2016/17 Calendar of Events
- Global Standards Meeting Schedule
- SEMI Japan Standards Award
  - JRSC Honor Award
    - Morihisa Hoga/Dai Nippon Printing
    - Makoto Ishikawa/Nisshinbo Mechatronics
    - Naokatsu Nishiguchi/SCREEN Business Support Solutions
    - Hideaki Ogihara
5 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

5.1 Document #5973: Line Item Revisions to SEMI E170-0416: Specification for Secured Foundation of Recipe Management System (SFORMS)

5.1.1 Line Item #1: Revise the format of ‘Service Message Description Table’.
5.1.2 Line Item #2: Correct editorial errors in ‘Table 46 Compliance Statement’.
5.1.3 Line Item #3: Add a section ‘Required Items for Each Implementation Step’ which provides a checklist of required items for each implementation step in Related Information.

Attachment: 07_5973_BallotReviewSheet_2016_1215_r1

6 Subcommittee and Task Force Reports

6.1 Equipment Information System Security (EISS) TF

Mitsuhiro Matsuda (Hitachi Kokusai Electric) reported for the EISS TF as follows, for Mitsune Sakamoto (Consultant), the leader, due to his absence at the meeting.

- TF started the activity in 2012
- E169 GUIDE FOR EQUIPMENT INFORMATION SYSTEM SECURITY; approved and published in 2014
- Discussed next standard theme
- Specification for Role Based Access Control (RBAC) was brought up
- The theme has been transferred to GEM300A activity
- Now no activity is planned with EISS TF

Attachment: 06_SEMI Staff Report 20161211_v1.1
• Proposal to I&C Committee; to conclude and disband the EISS Task Force.

Attachment: 08_EISS_Report

6.2 Fiducial Mark Interoperability (FMI) TF
Mitsuhiro Matsuda (Hitachi Kokusai Electric) reported for the FMI TF that there is no update.

6.3 GEM300 TF
Yoshihisa Takasaki (SCREEN Semiconductor Solutions) reported for the GEM300 TF. Of note:
- Cycle 8 Ballot result review
  - Reviewed on December 15, #5973 Line Item Revision to E170 SFORMS
    - TF member agreed to fail line item #3 to remove “Comply” column from table R1-2
    - Though Albert Fuchigami-san was agreed to withdrawal of his comment, line item 3 fail is necessary for SEMI standard development procedure.
- Proposal of SNARF revision
  - #6089 Revision to SEMI E170.1, subordinate standard of SFORMS
  - #6091 Line Item Revision to SEMI E174-1116 Specification for Wafer Job Management (WJM)

Attachment: 09_JA_GEM300TF_Report_20161216_R1

6.4 Japan I&C Maintenance TF
Mitsuhiro Matsuda (Hitachi Kokusai Electric) reported for the Japan I&C Maintenance TF. Of note:
- Proposal of Ballot submission of Line Item Revision to SEMI E91 (PSEM)
- Waiting for Proof of SEMI E99 and SEMI E99.1 (Carrier ID Reader/Writer)

7 Old Business
7.1 5 Year Review Check
Chie Yanagisawa (SEMI Japan) addressed the committee that the upcoming five year review documents will be SEMI E54.21-0614 and SEMI E54.19-0614.

7.2 SNARF Project Period Check
Chie Yanagisawa (SEMI Japan) addressed the committee that the oldest SNARF is #5973, which was initially approved in 2015.

7.3 R5601A Disapprove vote from Brian Rubow (Cimetrix Incorporated), Action Item 20161021-03
Mitsuhiro Matsuda (Hitachi Kokusai Electric) addressed the committee on this topic.

The action item 20161021-03 is SEMI Staff to ask the voter, Brian Rubow (Cimetrix Incorporated), to clarify the point that he does not satisfy of the technical reasons of his Disapprove vote because the I&C Japan TC Chapter did not understand the meaning of his technical reasons of this disapprove vote.

Mitsuhiro Matsuda stated that the Japan TC Chapter will not consider it because there has been no reply from Brian Rubow (Cimetrix) about R5601A Disapprove vote.
8 New Business

8.1 Explanation of concept of CUARAM: Centralized User Authentication & Role Authorization Management

Terry Asakawa (Tokyo Electron) explained this topic to the committee based on the material for the purpose of seeking if there is a need for it before its development.

Action Item: 20161216-01, SEMI Korea staff and SEMI Taiwan staff to send the materials for concept of CUARAM (Centralized User Authentication & Role Authorization Management) that Terry Asakawa (Tokyo Electron) explained at this meeting to the TC members in each region before the upcoming TC Chapter meeting and then to receive feedback from them at the TC Chapter meeting.

Attachment: 10_SEMI_Doc._6092_CUARAM_2016_1102cex

8.2 Ballot submission of #6090: Line Item Revision to SEMI E91-0600 (Reapproved 1109) “SPECIFICATION FOR PROBER SPECIFIC EQUIPMENT MODEL (FSEM)”

Tadashi Mochizuki (Tokyo Electron) addressed the committee on this topic.

Motion: To approve ballot submission of SEMI E91-0600 (Reapproved 1109) for Cycle 2-2017

By / 2nd: Tadashi Mochizuki (Tokyo Electron) / Mitsuhiro Matsuda (Hitachi Kokusai Electric)

Discussion: None

Vote: 9 in favor and 0 opposed. Motion Passed.

8.3 Revision to SNARF #6089: Line Item Revision to SEMI E170.1-0416 and SEMI E5-0813

Yoshihisa Takasaki (SCREEN Semiconductor Solutions) addressed the committee on this topic.

Motion: To approve revision to SNARF #6089: Line Item Revision to SEMI E170.1-0416 and SEMI E5-0813

By / 2nd: Yoshihisa Takasaki (SCREEN Semiconductor Solutions) / Naoko Murata (Tokyo Electron)

Discussion: None

Vote: 9 in favor and 0 opposed. Motion Passed.

8.4 Ballot submission of #6089: Line Item Revision to “SEMI E170.1-0416 SPECIFICATION FOR SECS-II PROTOCOL FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM”, “SEMI E170-0416, SPECIFICATION FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM (SFORMS)” and “SEMI E5-0813 SEMI EQUIPMENT COMMUNICATIONS STANDARD 2 MESSAGE CONTENT (SECS-II)” with title change.

Yoshihisa Takasaki (SCREEN Semiconductor Solutions) addressed the committee on this topic.

Motion: To approve ballot submission of #6089: Line Item Revision to SEMI E170.1-0416, SEMI E170-0416, and SEMI E5-0813 with title change for Cycle 2-2017

By / 2nd: Yoshihisa Takasaki (SCREEN Semiconductor Solutions) / Naoko Murata (Tokyo Electron)

Discussion: None

Vote: 9 in favor and 0 opposed. Motion Passed.

8.5 Revision to SNARF #6091: Line Item Revision to SEMI E174-1116 (SEMI Doc. R5601A): Specification for Wafer Job Management (WJM)

Yoshihisa Takasaki (SCREEN Semiconductor Solutions) addressed the committee on this topic.

Motion: To approve revision to SNARF #6091: Line Item Revision to SEMI E174-1116 (SEMI Doc. R5601A)

By / 2nd: Yoshihisa Takasaki (SCREEN Semiconductor Solutions) / Naoko Murata (Tokyo Electron)
8.6 Ballot submission of #6091: Line Item Revision to SEMI E174-1116 (SEMI Doc. R5601A): Specification for Wafer Job Management (WJM)

Yoshihisa Takasaki (SCREEN Semiconductor Solutions) addressed the committee on this topic.

Motion: To approve ballot submission of #6091: Line Item Revision to SEMI E174-1116 for Cycle 2-2017

By / 2nd: Yoshihisa Takasaki (SCREEN Semiconductor Solutions) / Naoko Murata (Tokyo Electron)

Discussion: None

Vote: 9 in favor and 0 opposed. Motion Passed.

8.7 Proposal to add compliance table to Related Information of SEMI E170: Specification for Secured Foundation of Recipe Management System (SFORMS)

Naoko Murata (Tokyo Electron) addressed the committee on this topic.

Motion: To authorize to publish addition of the proposed section, the compliance table, as R1-8 to Related Information 1 of SEMI E170

By / 2nd: Naoko Murata (Tokyo Electron) / Yuko Toyoshima (Hitachi High Technologies)

Discussion: None

Vote: 9 in favor and 0 opposed. Motion Passed.

This proposal will be forwarded to GCS, to get subsequently approval, and be forwarded to A&R.

Attachment: 11_Proposal_to_Add_Compliance_Table_to_RI_2016_1215

8.8 Discharge for Equipment Information System Security (EISS) TF

Mitsuhiro Matsuda (Hitachi Kokusai Electric) addressed the committee on this topic.

Motion: To approve discharge for EISS TF

By / 2nd: Mitsuhiro Matsuda (Hitachi Kokusai Electric) / Yoshihisa Takasaki (SCREEN Semiconductor Solutions)

Discussion: None

Vote: 9 in favor and 0 opposed. Motion Passed.

9 Next Meeting and Adjournment

The next meeting is scheduled for Friday, April 21, 2017, 13:30-17:00, at SEMI Japan office, Tokyo. See http://www.semi.org/en/events for the current list of meeting schedules.

Having no further business, a motion was made to adjourn. Adjournment was at 16:30.
Respectfully submitted by:
Chie Yanagisawa
Manager
SEMI Japan
Phone: +81.3.3222.5863
Email: cyanagisawa@semi.org

Minutes tentatively approved by:

<table>
<thead>
<tr>
<th>Name</th>
<th>Co-chair</th>
<th>Date</th>
</tr>
</thead>
<tbody>
<tr>
<td>Takayuki Nishimura (SCREEN Semiconductor Solutions)</td>
<td></td>
<td>April 18, 2017</td>
</tr>
<tr>
<td>Mitsuhiro Matsuda (Hitachi Kokusai Electric)</td>
<td></td>
<td>April 17, 2017</td>
</tr>
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**Table 13 Index of Available Attachments**

<table>
<thead>
<tr>
<th>Title</th>
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<tbody>
<tr>
<td>01_Required_Elements_Reg_20150327_E+J</td>
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#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.